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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# IRF7422D2PbF

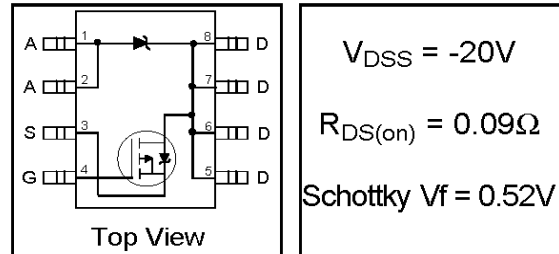
## FETKY™ MOSFET & Schottky Diode

- Co-packaged HEXFET® Power MOSFET and Schottky Diode
- Ideal For Buck Regulator Applications
- P-Channel HEXFET
- Low  $V_F$  Schottky Rectifier
- Generation 5 Technology
- SO-8 Footprint
- Lead-Free

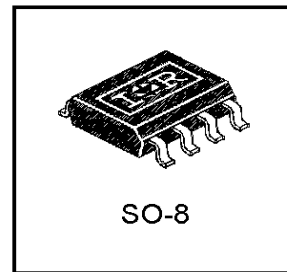
### Description

The FETKY™ family of Co-packaged HEXFETs and Schottky diodes offer the designer an innovative board space saving solution for switching regulator and power management applications. Generation 5 HEXFETs utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. Combining this technology with International Rectifier's low forward drop Schottky rectifiers results in an extremely efficient device suitable for use in a wide variety of portable electronics applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics. The SO-8 package is designed for vapor phase, infrared or wave soldering techniques.



$V_{DSS} = -20V$   
 $R_{DS(on)} = 0.09\Omega$   
 Schottky  $V_f = 0.52V$



### Absolute Maximum Ratings

Parameter	Maximum	Units
$I_D @ T_A = 25^\circ C$	-4.3	A
$I_D @ T_A = 70^\circ C$	-3.4	
$I_{DM}$	-33	
$P_D @ T_A = 25^\circ C$	2.0	W
$P_D @ T_A = 70^\circ C$	1.3	
	16	mW/°C
$V_{GS}$	$\pm 12$	V
$dv/dt$	-5.0	V/ns
$T_J, T_{STG}$	-55 to +150	°C

### Thermal Resistance Ratings

Parameter	Maximum	Units
$R_{\theta JA}$	62.5	°C/W

### Notes:

- ① Repetitive rating – pulse width limited by max. junction temperature (see fig. 11)
- ②  $I_{SD} \leq -2.2A$ ,  $di/dt \leq -50A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 150^\circ C$
- ③ Pulse width  $\leq 300\mu s$  – duty cycle  $\leq 2\%$
- ④ Surface mounted on FR-4 board,  $t \leq 10sec$ .

## MOSFET Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	-20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	0.07	0.09	Ω	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2.2A ③
		—	0.115	0.14		V <sub>GS</sub> = -2.7V, I <sub>D</sub> = -1.8A ③
V <sub>GS(th)</sub>	Gate Threshold Voltage	-0.70	—	—	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
g <sub>fs</sub>	Forward Transconductance	4.0	—	—	S	V <sub>DS</sub> = -16V, I <sub>D</sub> = -2.2A
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	-1.0	μA	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V
		—	—	-25		V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	-100	nA	V <sub>GS</sub> = -12V
	Gate-to-Source Reverse Leakage	—	—	100		V <sub>GS</sub> = 12V
Q <sub>g</sub>	Total Gate Charge	—	15	22	nC	I <sub>D</sub> = -2.2A
Q <sub>gs</sub>	Gate-to-Source Charge	—	2.2	3.3		V <sub>DS</sub> = -16V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	6.0	9.0		V <sub>GS</sub> = -4.5V, See Fig. 6 and 9 ③
t <sub>d(on)</sub>	Turn-On Delay Time	—	8.4	—	ns	V <sub>DD</sub> = -10V
t <sub>r</sub>	Rise Time	—	26	—		I <sub>D</sub> = -2.2A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	51	—		R <sub>G</sub> = 6.0Ω
t <sub>f</sub>	Fall Time	—	33	—		R <sub>D</sub> = 4.5Ω, See Fig. 10 ③
C <sub>iss</sub>	Input Capacitance	—	610	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	310	—		V <sub>DS</sub> = -15V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	170	—		f = 1.0MHz, See Fig. 5

## MOSFET Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	-2.5	A	
I <sub>SM</sub>	Pulsed Source Current (Body Diode)	—	—	-17		
V <sub>SD</sub>	Body Diode Forward Voltage	—	—	-1.0	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = -1.8A, V <sub>GS</sub> = 0V
t <sub>rr</sub>	Reverse Recovery Time (Body Diode)	—	56	84	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = -2.2A
Q <sub>rr</sub>	Reverse Recovery Charge	—	71	110	nC	di/dt = -100A/μs ③

## Schottky Diode Maximum Ratings

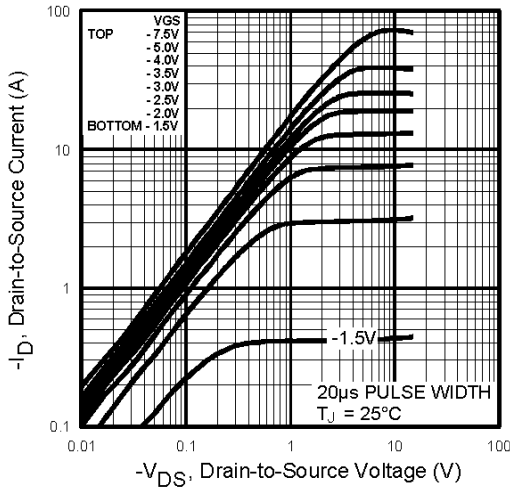
	Parameter	Max.	Units	Conditions
I <sub>f</sub> (av)	Max. Average Forward Current	2.8	A	50% Duty Cycle. Rectangular Wave, T <sub>c</sub> = 25°C
		1.8		50% Duty Cycle. Rectangular Wave, T <sub>c</sub> = 70°C
I <sub>SM</sub>	Max. peak one cycle Non-repetitive Surge current	200	A	5μs sine or 3μs Rect. pulse
		20		10ms sine or 6ms Rect. pulse
				Following any rated load condition & with V <sub>rrm</sub> applied

## Schottky Diode Electrical Specifications

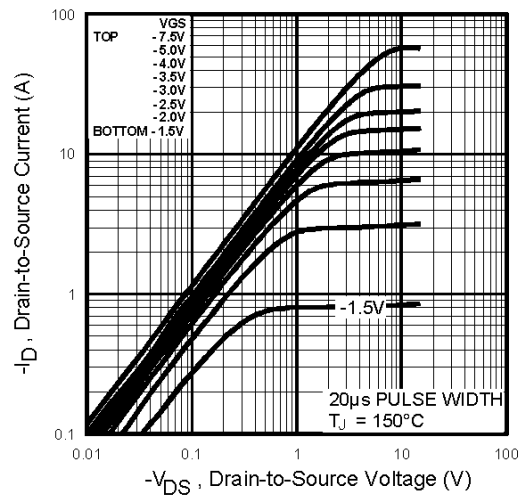
	Parameter	Max.	Units	Conditions
V <sub>fm</sub>	Max. Forward voltage drop	0.57	V	I <sub>f</sub> = 3.0, T <sub>J</sub> = 25°C
		0.77		I <sub>f</sub> = 6.0, T <sub>J</sub> = 25°C
		0.52		I <sub>f</sub> = 3.0, T <sub>J</sub> = 125°C
		0.79		I <sub>f</sub> = 6.0, T <sub>J</sub> = 125°C
I <sub>rm</sub>	Max. Reverse Leakage current	0.13	mA	V <sub>r</sub> = 20V, T <sub>J</sub> = 25°C
		18		T <sub>J</sub> = 125°C
C <sub>t</sub>	Max. Junction Capacitance	310	pF	V <sub>r</sub> = 5Vdc ( 100kHz to 1 MHz) 25°C
dv/dt	Max. Voltage Rate of Charge	4900	V/μs	Rated V <sub>r</sub>

( HEXFET is the reg. TM for International Rectifier Power MOSFET's )

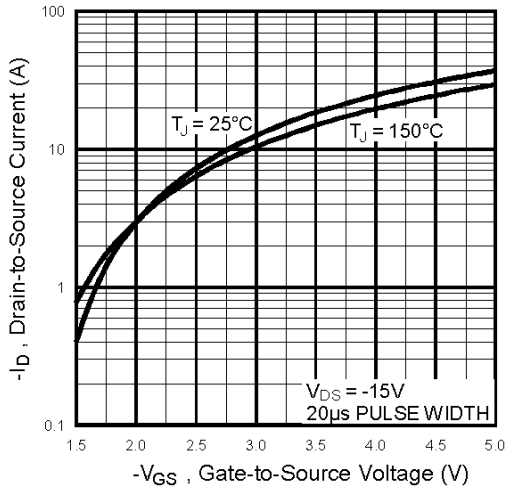
## Power Mosfet Characteristics



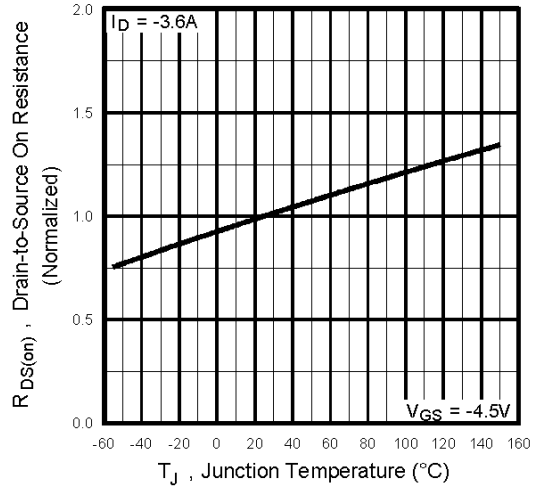
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics

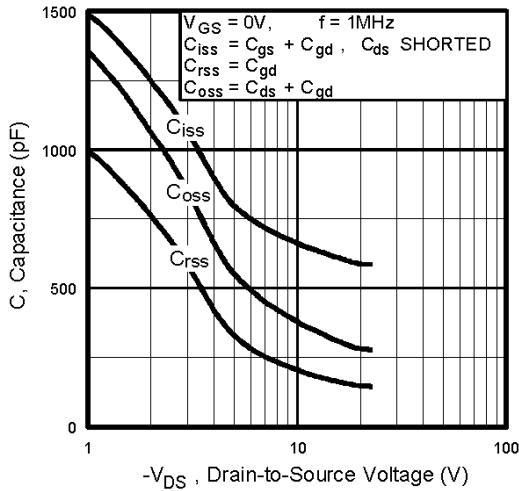


**Fig 3.** Typical Transfer Characteristics

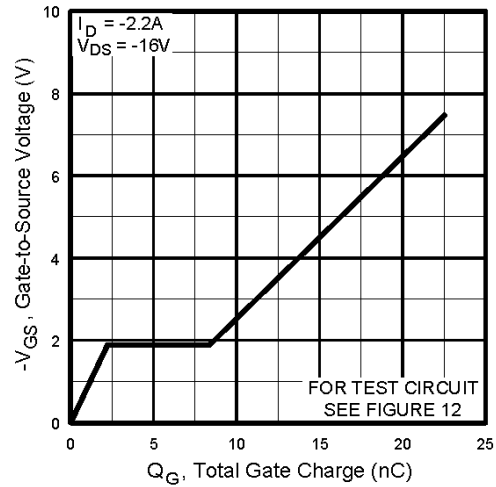


**Fig 4.** Normalized On-Resistance Vs. Temperature

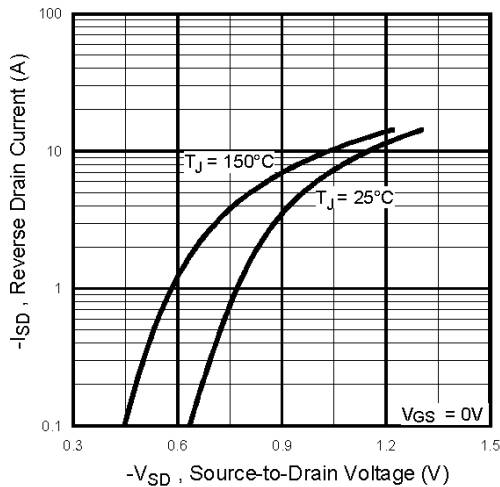
## Power Mosfet Characteristics



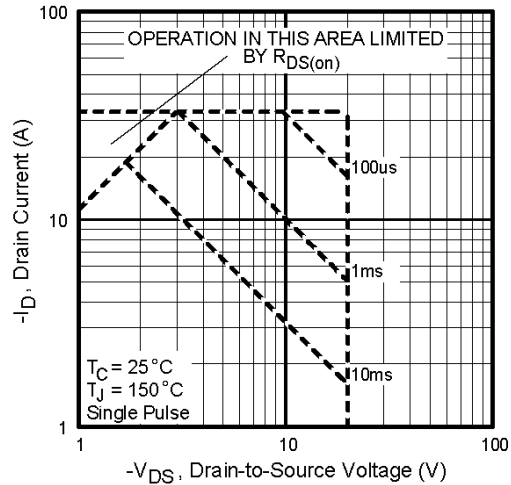
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage

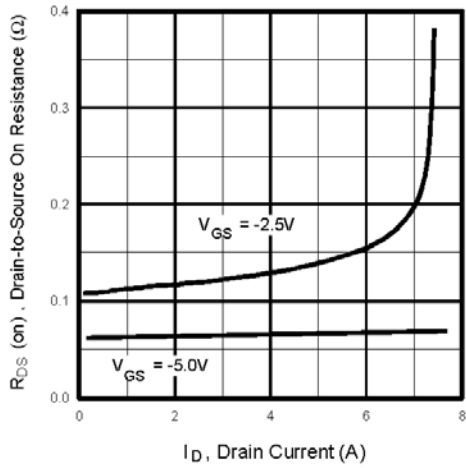
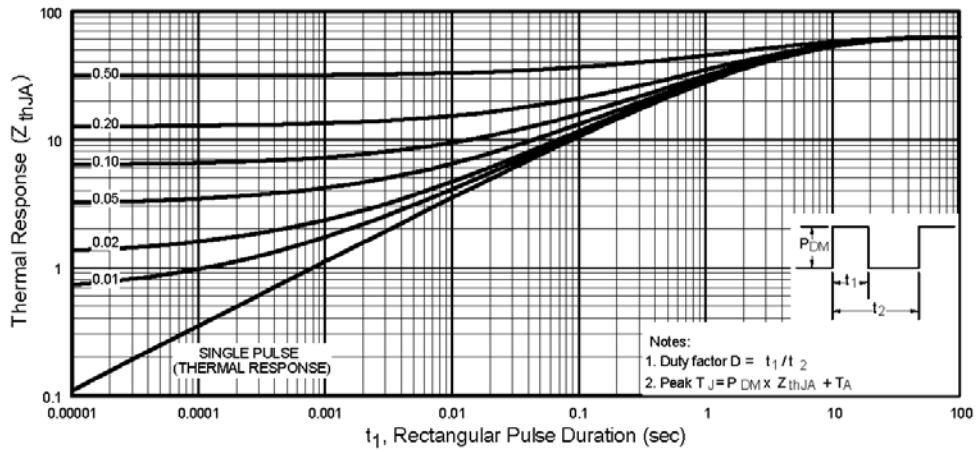


**Fig 7.** Typical Source-Drain Diode Forward Voltage

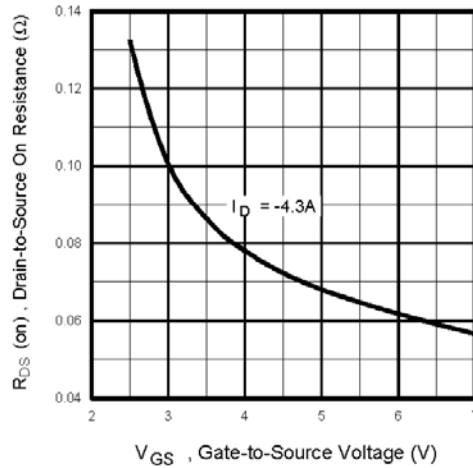


**Fig 8.** Maximum Safe Operating Area

## Power Mosfet Characteristics

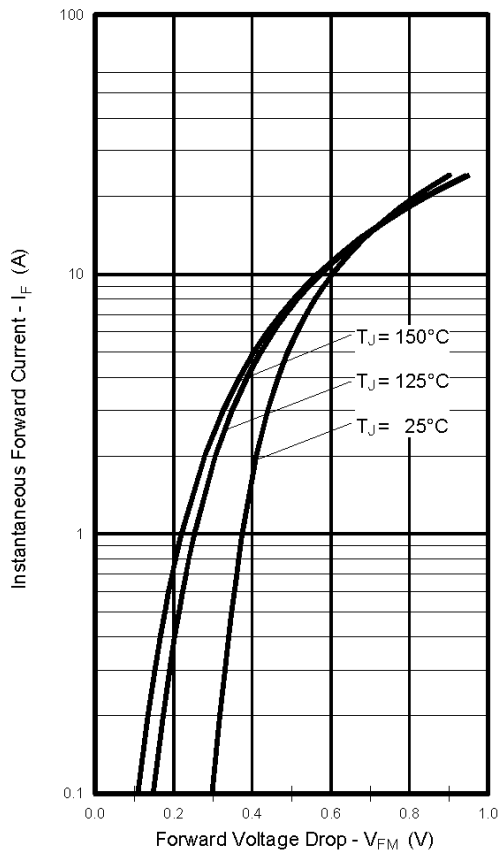


**Fig 10.** Typical On-Resistance Vs. Drain Current

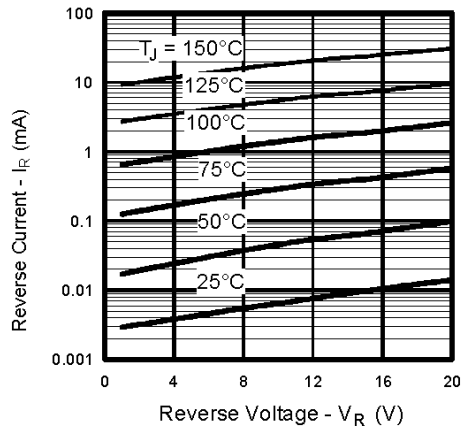


**Fig 11.** Typical On-Resistance Vs. Gate Voltage

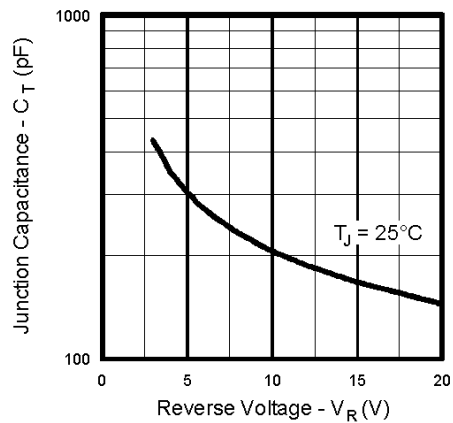
## Schottky Diode Characteristics



**Fig. 12** - Typical Forward Voltage Drop Characteristics

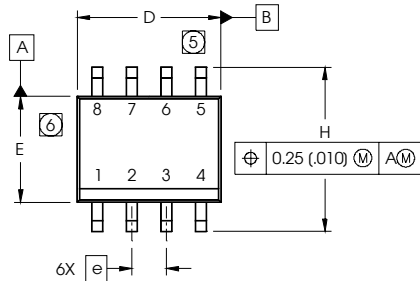


**Fig. 13** - Typical Values of Reverse Current Vs. Reverse Voltage

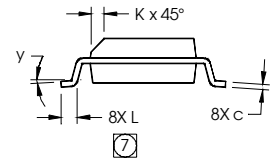
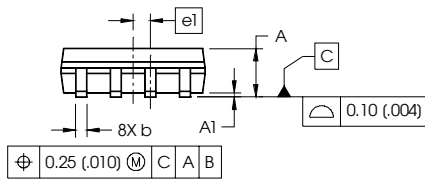


**Fig. 14** - Typical Junction Capacitance Vs. Reverse Voltage

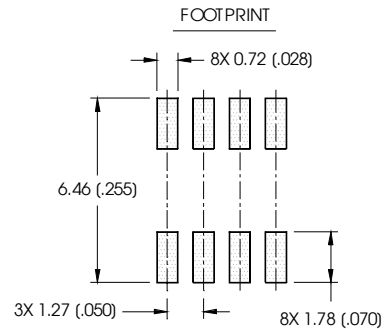
## SO-8 (Fetky) Package Outline



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°

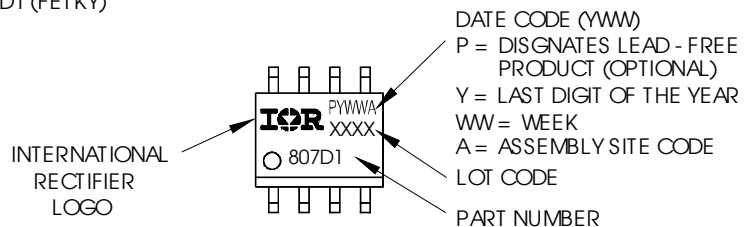


- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
  2. CONTROLLING DIMENSION: MILLIMETER
  3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
  4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
  - ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
  - ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
  - ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



## SO-8 (Fetky) Part Marking Information

EXAMPLE: THIS IS AN IRF7807D1 (FETKY)



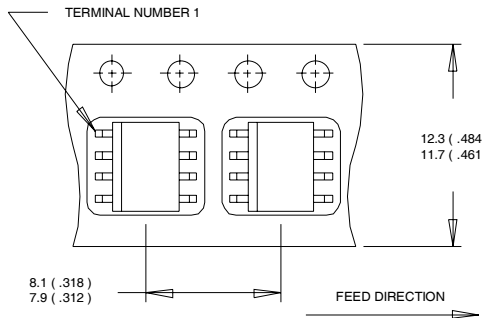


# IRF7422D2PbF

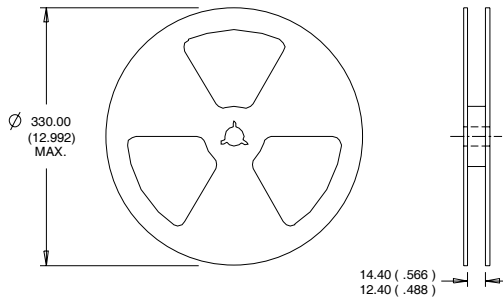


## SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Consumer market.  
Qualifications Standards can be found on IR's Web site.



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